Unit: mm

TOSHIBA INSULATED GATE BIPOLAR TRANSISTOR SILICON N CHANNEL IGBT

GT15M321

HIGH POWER SWITCHING APPLICATIONS

• Fourth-generation IGBT

• FRD included between emitter and collector

• Enhancement mode type

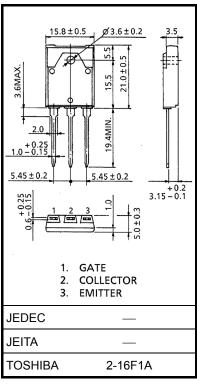
• High speed : $t_f = 0.20 \mu s$ (TYP.) (IC = 15 A)

• Low saturation voltage $: V_{CE (sat)} = 1.8V (TYP.)$

 $(I_C = 15A)$

ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

| CHARACTERISTIC | | SYMBOL | RATING | UNIT | |
|---|-----|------------------|---------|------|--|
| Collector-Emitter Voltage | | V _{CES} | 900 | V | |
| Gate-Emitter Voltage | | V _{GES} | ±25 | V | |
| Collector Current | DC | IC | 15 | Α | |
| | 1ms | I _{CP} | 30 | A . | |
| Emitter-Collector Foward Current | DC | l _F | 15 | А | |
| | 1ms | I _{FM} | 120 | | |
| Collector Power Dissipation (Tc = 25°C) | | PC | 55 | W | |
| Junction Temperature | | Tj | 150 | °C | |
| Storage Temperature Range | | T _{stg} | -55~150 | °C | |



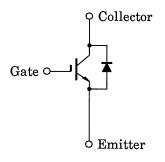
Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high

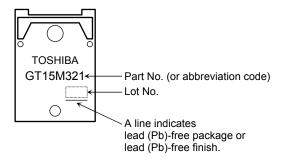
temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

EQUIVALENT CIRCUIT



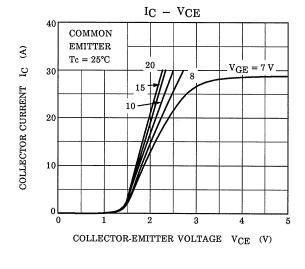
MARKING

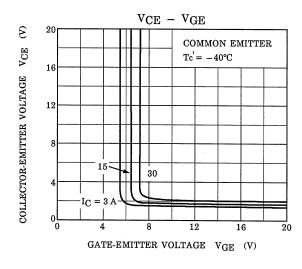


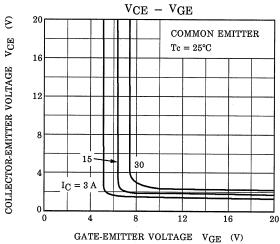
ELECTRICAL CHARACTERISTICS (Ta=25°C)

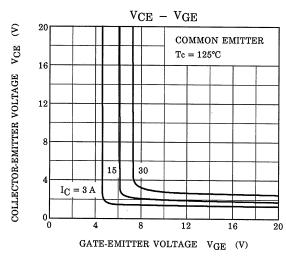
| CHARACTERISTIC | | SYMBOL | TEST CONDITION | MIN | TYP. | MAX | UNIT |
|--------------------------------------|---------------|-----------------------|--|-----|------|------|--------|
| Gate Leakage Current | | I _{GES} | V _{GE} = ±25 V, V _{CE} = 0 | _ | _ | ±500 | nA |
| Collector Cut-off Current | | I _{CES} | V _{CE} = 900 V, V _{GE} = 0 | _ | _ | 1.0 | mA |
| Gate-Emitter Cut-off Voltage | | V _{GE} (OFF) | I _C = 15 mA, V _{CE} = 5 V | 3.0 | _ | 6.0 | V |
| Collector-Emitter Saturation Voltage | | V _{CE} (sat) | I _C = 15 A, V _{GE} = 15 V | _ | 1.8 | 2.5 | V |
| Input Capacitance | | C _{ies} | V _{CE} = 10 V, V _{GE} = 0, f = 1 MHz | _ | 1200 | _ | pF |
| Switching Time | Rise Time | t _r | 15 V 100 Ω 3 600 V | _ | 0.20 | _ | μs |
| | Turn-on Time | t _{on} | | _ | 0.30 | _ | |
| | Fall Time | t _f | | _ | 0.20 | 0.40 | |
| | Turn-off Time | t _{off} | | _ | 0.50 | _ | |
| Emitter-Collector Forward Voltage | | V _F | I _{EC} = 15 A, V _{GE} = 0 | _ | 1.5 | 2.0 | V |
| Reverse Recovery Time | | t _{rr} | I _F = 15 A, V _{GE} = 0 di / dt = -20 A / μs | _ | 0.7 | 2.5 | μS |
| Thermal Resistance R | | R _{th (j−c)} | IGBT | _ | _ | 2.27 | °C / W |
| Thermal Resistance | | R _{th (j−c)} | Diode | _ | _ | 2.27 | °C / W |

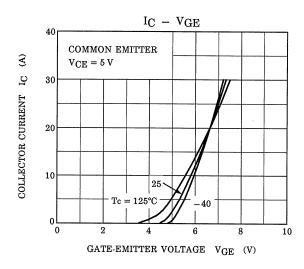
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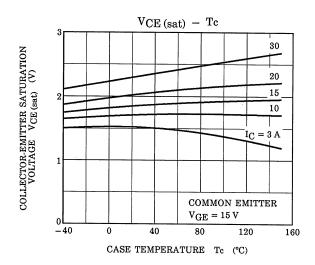


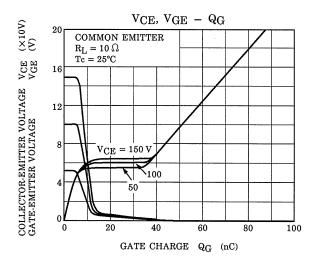


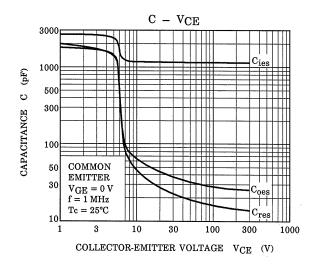


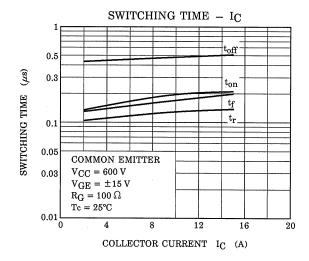


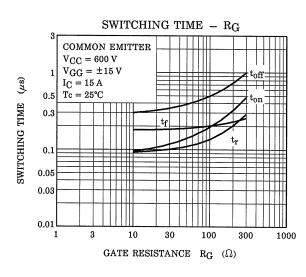


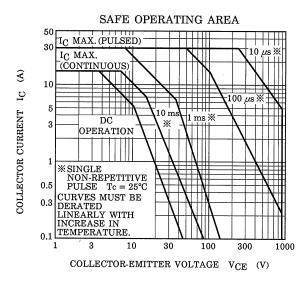


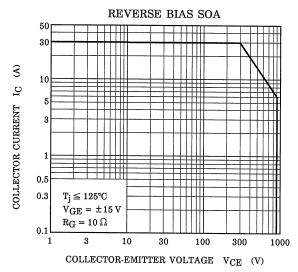


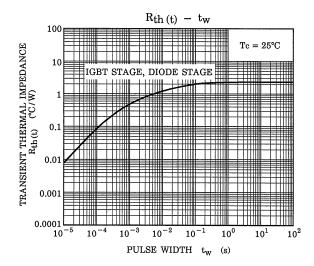


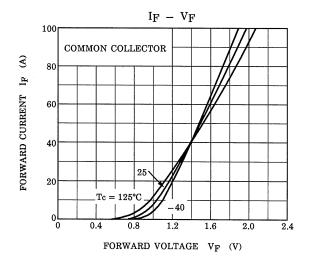


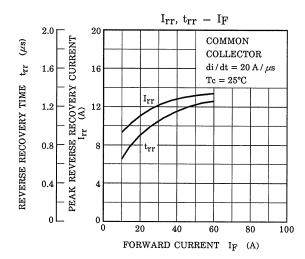


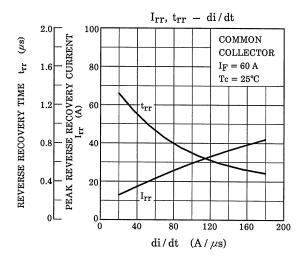


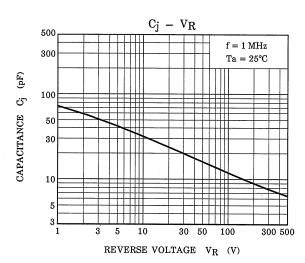












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